

ABSTRACT OF THE DISCLOSURE

A tape carrier type semiconductor device includes a flexible substrate, on which a driver circuit is mounted and on whose surface wiring is formed. Formed in the flexible substrate are the first slit for releasing external stress and the second slit for folding the 5 tape carrier type semiconductor device. A connector for connecting both sides of the first slit is prepared at the center of the slit, whereby the unnecessary warp of the tape carrier type semiconductor device can be reduced.

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